



BCZ120N16M1

N-Channel Silicon Carbide Power MOSFET

1200 V, 118 A, 16 mΩ

Features

- High switching speed with a low gate charge
- Fast intrinsic diode with low reverse recovery
- Robust Avalanche Capability
- 100% Avalanche Tested
- Pb-free, Halogen Free, and RoHS Compliant

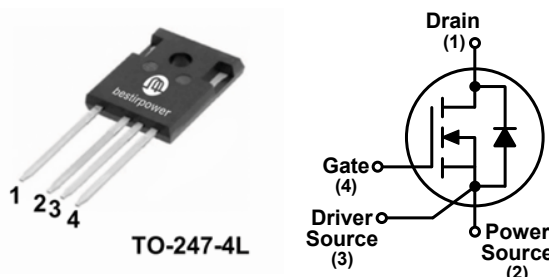
$BV_{DSS, T_C=25^\circ C}$	$I_D, T_C=25^\circ C$	$R_{DS(on), typ}$	$Q_{g, typ}$
1200 V	118 A	16 mΩ	152 nC

Benefits

- System efficiency improvement
- Higher frequency applicability
- Increased power density
- Reduced cooling effort

Applications

- Solar inverter
- EV charging station
- UPS
- Industrial power supply



Absolute Maximum Ratings ($T_J = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit	
V_{DSS}	Drain to Source Voltage	1200	V	
V_{GS}	Gate to Source Voltage (DC)	-10 / +22	V	
V_{GSop}	Recommended Operation Value	-5...-3 / +18	V	
I_D	Drain Current	$V_{GS} = 18 V, (T_C = 25^\circ C)$	118	A
		$V_{GS} = 18 V, (T_C = 100^\circ C)$	84	
I_{DM}	Drain Current	Pulsed (Note1)	295	A
P_D	Power Dissipation	$(T_C = 25^\circ C)$	500	W
		Derate Above $25^\circ C$	3.3	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 175	°C	
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds	260	°C	

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	
T_{sold}	Soldering temperature, wave soldering only allowed at leads	260	°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	1200	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$	-	1	100	μA
		$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}, T_J = 175^\circ\text{C}$	-	10	-	
I_{GSS}	Gate-Source Leakage Current	$V_{GS} = +22\text{ V}, V_{DS} = 0\text{ V}$	-	-	+100	nA
		$V_{GS} = -10\text{ V}, V_{DS} = 0\text{ V}$	-	-	-100	

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 24\text{ mA}$ (tested after $V_{GS} = 22\text{ V}, 1\text{ ms pulse}$)	2.0	3.0	4.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 18\text{ V}, I_D = 50\text{ A}$	-	16.0	22.4	$\text{m}\Omega$
		$V_{GS} = 18\text{ V}, I_D = 50\text{ A}, T_J = 175^\circ\text{C}$	-	25.6	-	
		$V_{GS} = 15\text{ V}, I_D = 50\text{ A}$	-	21.5	-	
g_{fs}	Transconductance	$V_{DS} = 20\text{ V}, I_D = 50\text{ A}$	-	32.7	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 800\text{ V}, V_{GS} = 0\text{ V}, f = 250\text{ kHz}$	-	4063	-	pF
C_{oss}	Output Capacitance		-	227	-	
C_{riss}	Reverse Capacitance		-	3	-	
E_{oss}	Stored Energy in Output Capacitance	$V_{DS} = 0\text{ V to } 800\text{ V}, V_{GS} = 0\text{ V}$	-	94	-	μJ
$C_{o(er)}$	Energy Related Output Capacitance		-	295	-	pF
$C_{o(tr)}$	Time Related Output Capacitance		-	476	-	
$Q_{g(tot)}$	Total Gate Charge	$V_{DS} = 800\text{ V}, I_D = 50\text{ A},$ $V_{GS} = -3\text{ V} / 18\text{ V},$ Inductive load	-	152	-	nC
Q_{gs}	Gate to Source Charge		-	49	-	
Q_{gd}	Gate to Drain "Miller" Charge		-	29	-	
R_G	Internal Gate Resistance	$f = 1\text{ MHz}, V_{AC} = 30\text{ mV open drain}$	-	2.7	-	Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 800\text{ V}, I_D = 50\text{ A},$ $V_{GS} = -3\text{ V} / 18\text{ V}, R_G = 4.7\ \Omega,$ Inductive load	-	32	-	ns
t_r	Turn-On Rise Time		-	25	-	
$t_{d(off)}$	Turn-Off Delay Time		-	65	-	
t_f	Turn-Off Fall Time		-	11	-	
E_{on}	Turn-on Switching Energy		-	539	-	μJ
E_{off}	Turn-off Switching Energy		-	302	-	
E_{tot}	Total Switching Energy		-	841	-	

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Source-Drain Diode Characteristics						
I_S	Continuous Diode Forward Current	$V_{GS} = -3\text{ V}$	-	-	105	A
I_{SM}	Pulsed Diode Forward Current	$V_{GS} = -3\text{ V}$ (Note1)	-	-	295	
V_{SD}	Diode Forward Voltage	$V_{GS} = -3\text{ V}, I_{SD} = 50\text{ A}$	-	4.0	-	V
t_{rr}	Reverse Recovery Time	$V_{DD} = 800\text{ V}, I_{SD} = 50\text{ A},$ $di_F/dt = 3000\text{ A}/\mu\text{s},$ Includes Q_{oss}	-	22	-	ns
Q_{rr}	Reverse Recovery Charge		-	486	-	nC
I_{rrm}	Peak Reverse Recovery Current		-	37	-	A

※Note 1 : Limited by maximum junction temperature.

Typical Performance Characteristics

Figure 1. On-Region Characteristics $T_J = -40^\circ\text{C}$

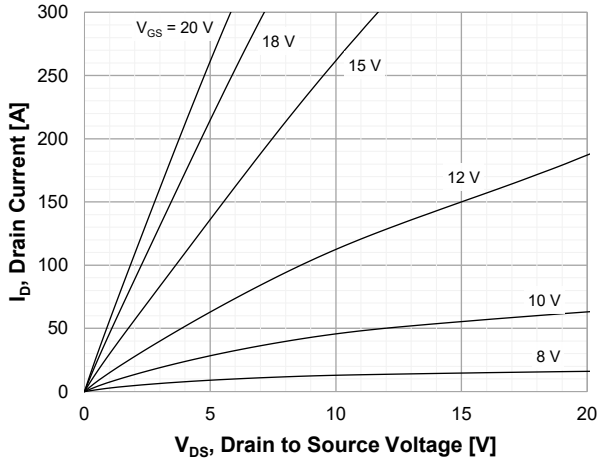


Figure 2. On-Region Characteristics $T_J = 25^\circ\text{C}$

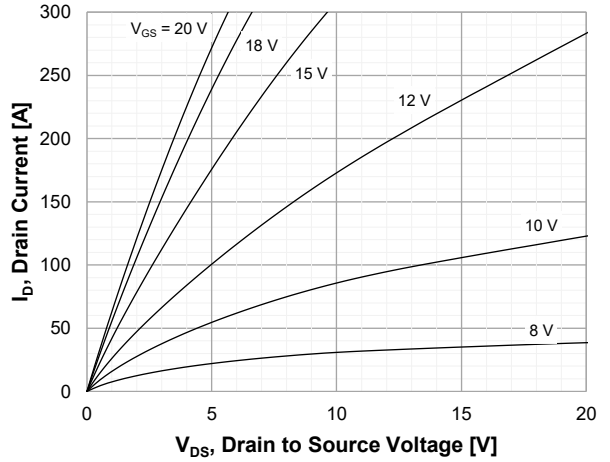


Figure 3. On-Region Characteristics $T_J = 175^\circ\text{C}$

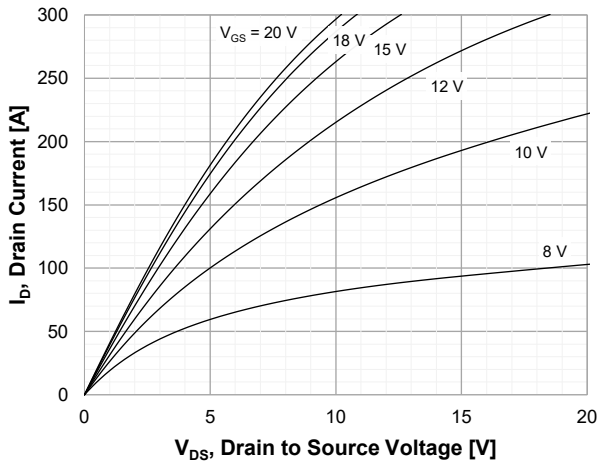


Figure 4. Normalized On-Resistance Characteristics vs. Temperature

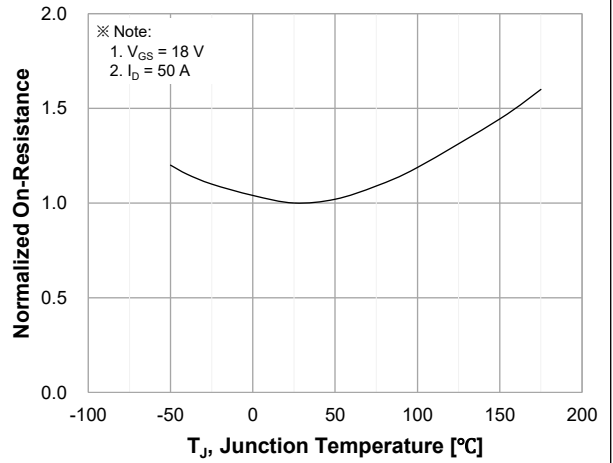


Figure 5. Transfer Characteristics

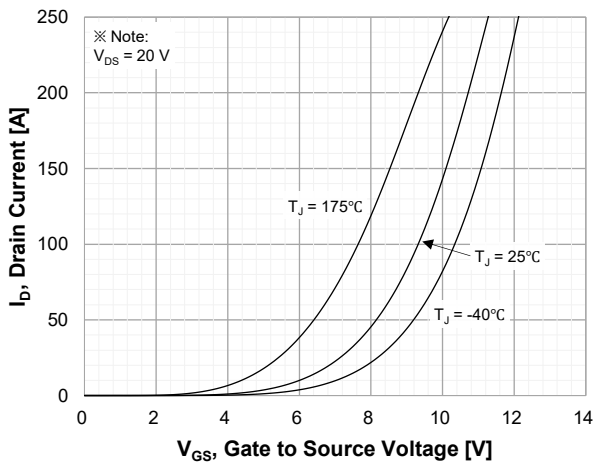
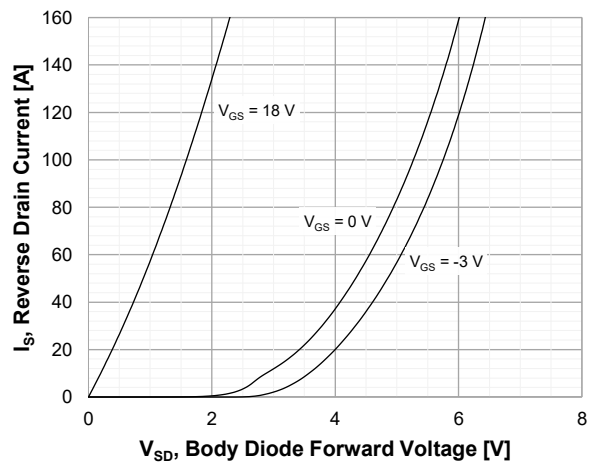


Figure 6. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = -40^\circ\text{C}$



Typical Performance Characteristics

Figure 7. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = 25^\circ\text{C}$

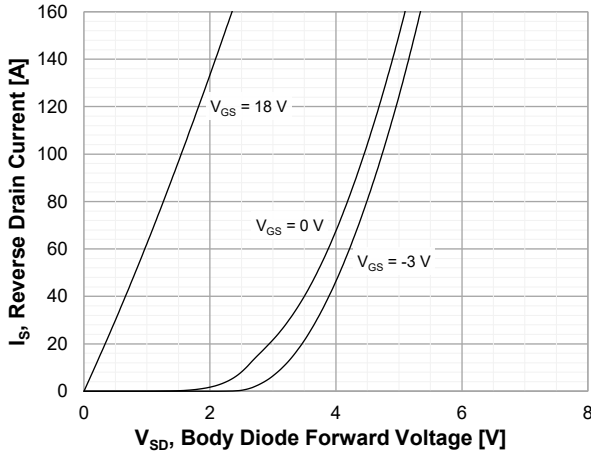


Figure 8. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = 175^\circ\text{C}$

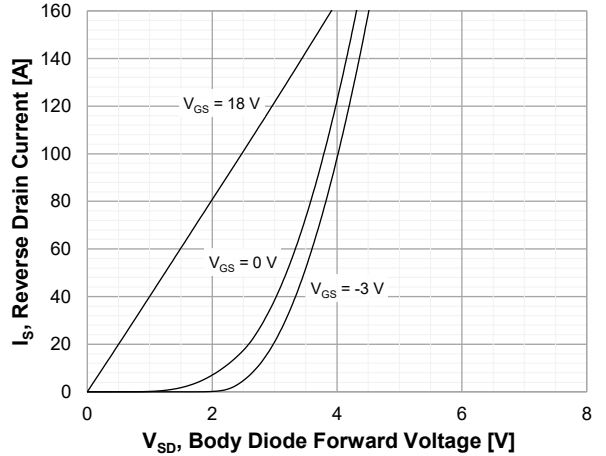


Figure 9. Threshold Voltage vs. Temperature

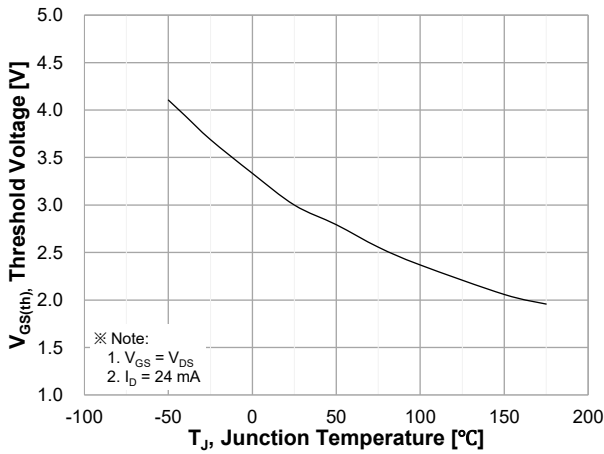


Figure 10. Gate Charge Characteristics

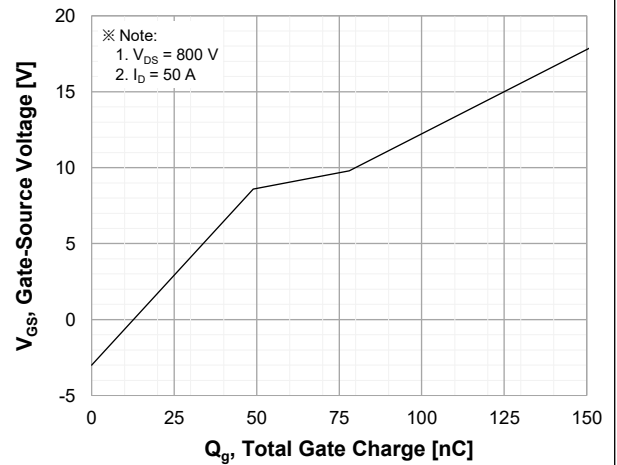


Figure 11. Stored Energy in Output Capacitance

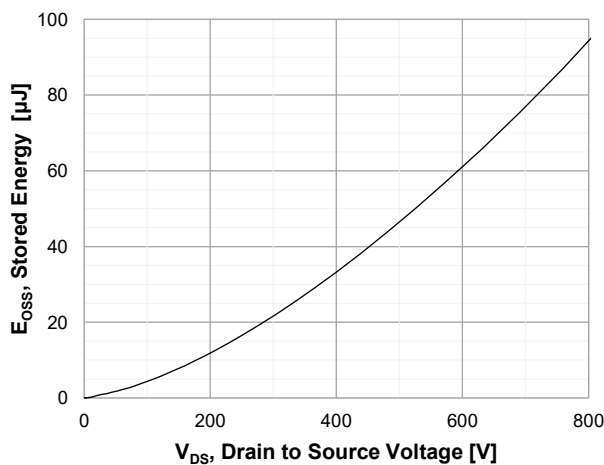
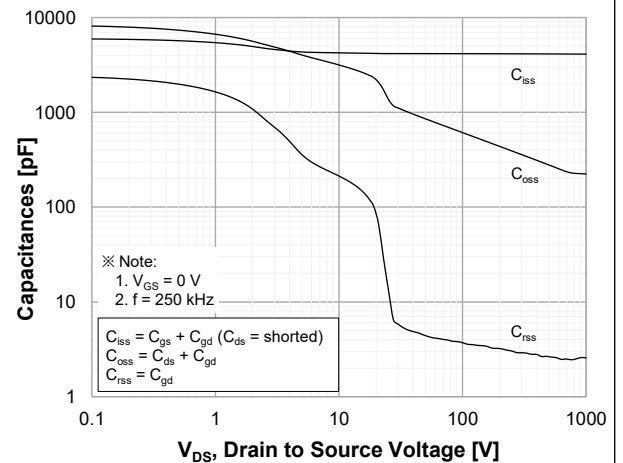


Figure 12. Capacitance Characteristics



Typical Performance Characteristics

Figure 13. Continuous Drain Current Derating vs. Case Temperature

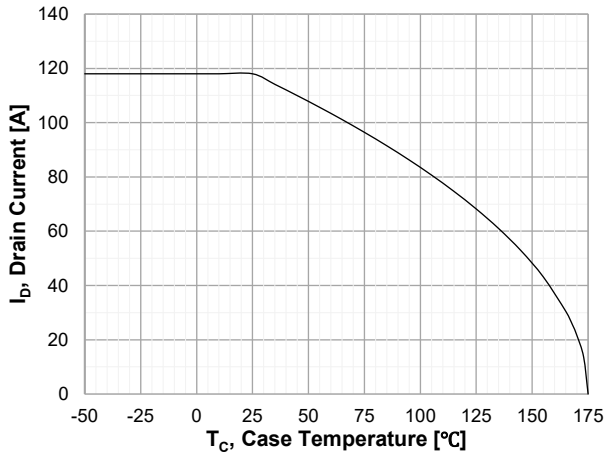


Figure 14. Maximum Power Dissipation Derating vs. Case Temperature

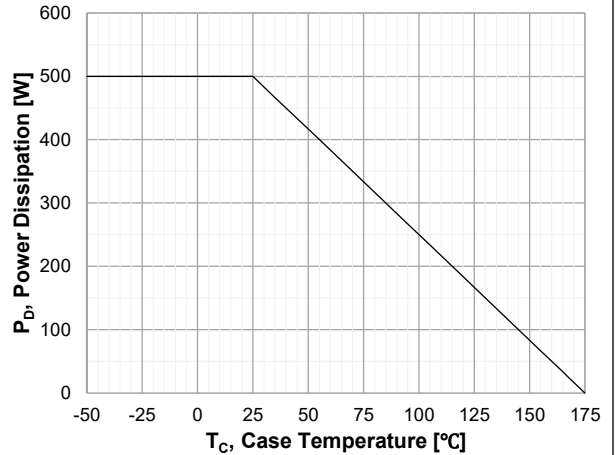


Figure 15. Typ. Switching Losses vs. Drain Current

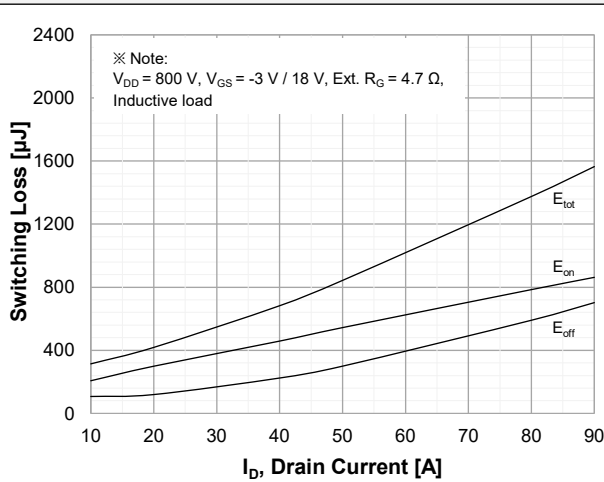


Figure 16. Typ. Switching Losses vs. Gate Resistance

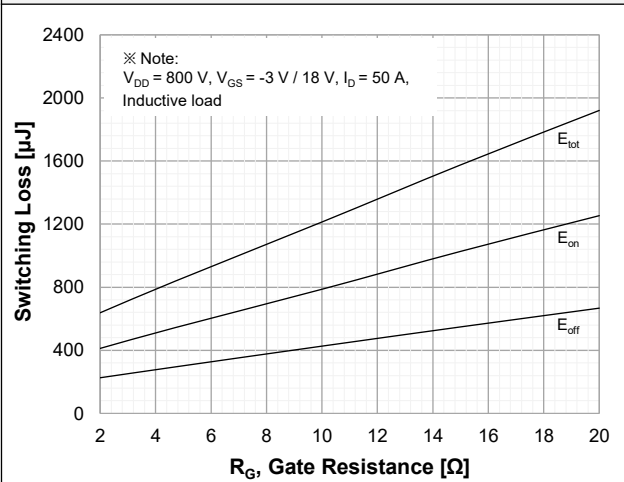


Figure 17. Typ. Switching Losses vs. Drain Current

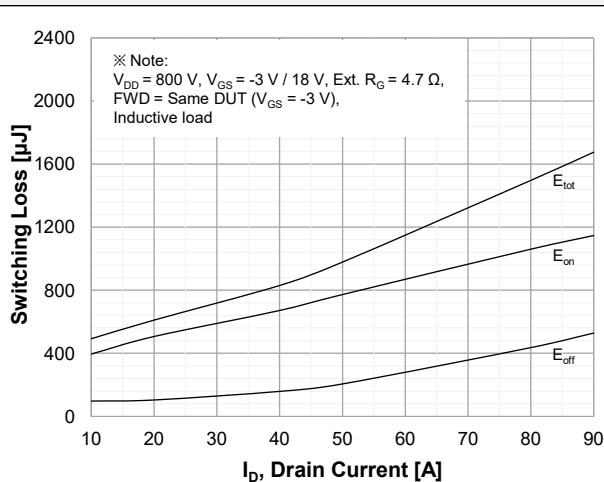
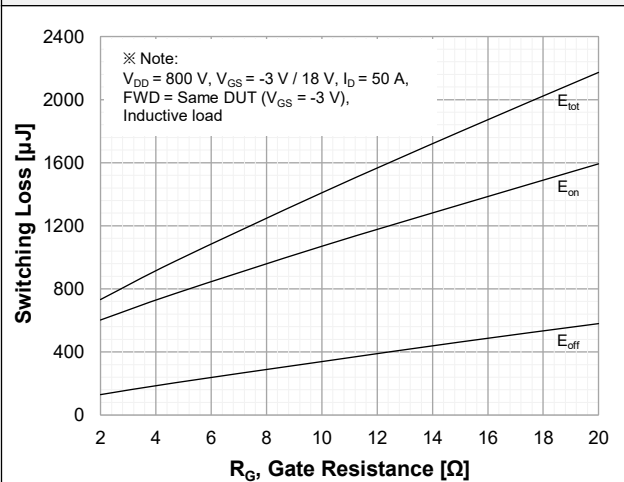


Figure 18. Typ. Switching Losses vs. Gate Resistance



Typical Performance Characteristics

Figure 19. Maximum Safe Operating Area

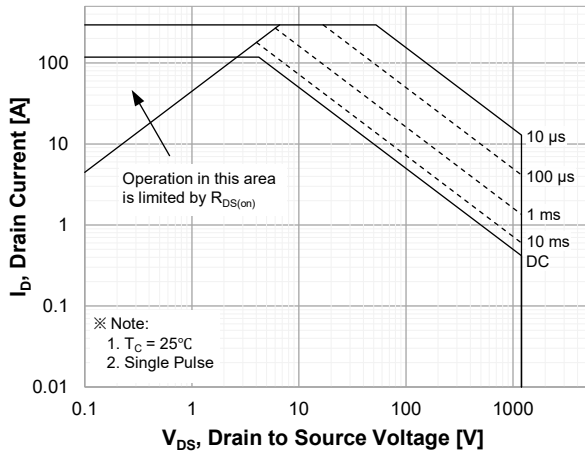


Figure 20. Transient Thermal Response Curve

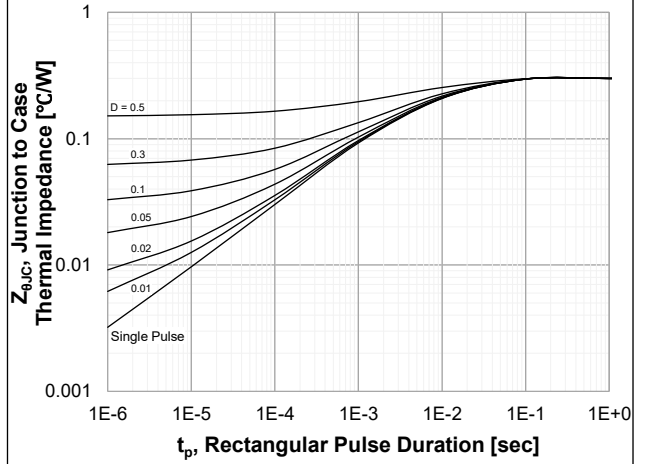


Figure 21. Inductive Load Switching Test Circuit and Waveforms

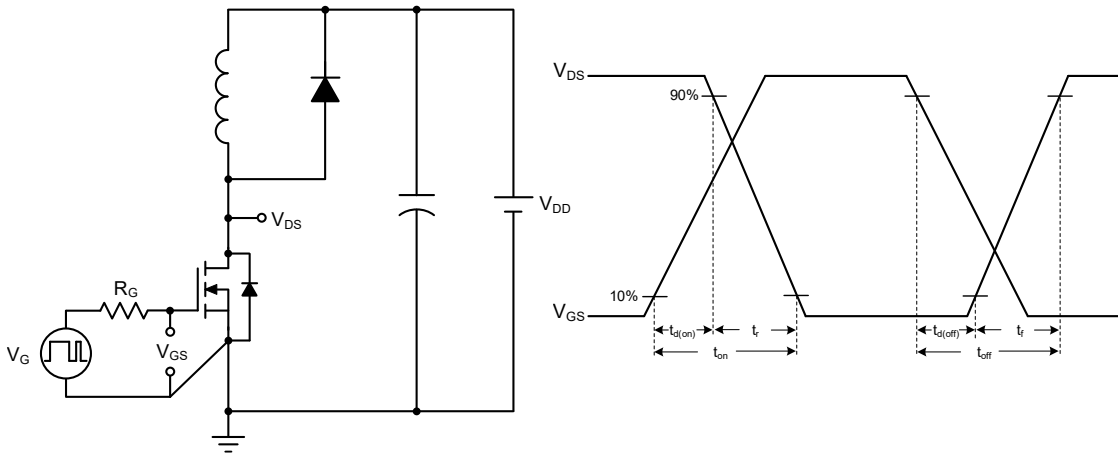
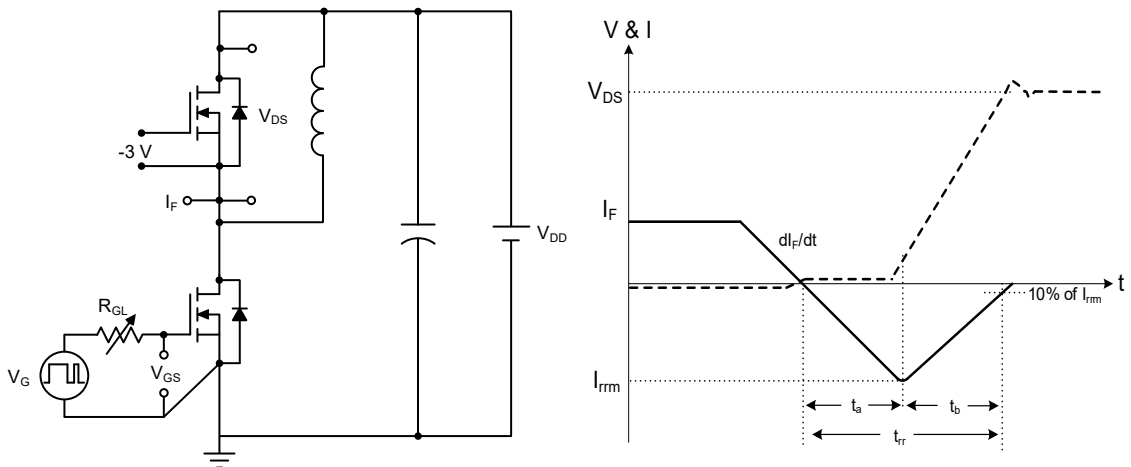
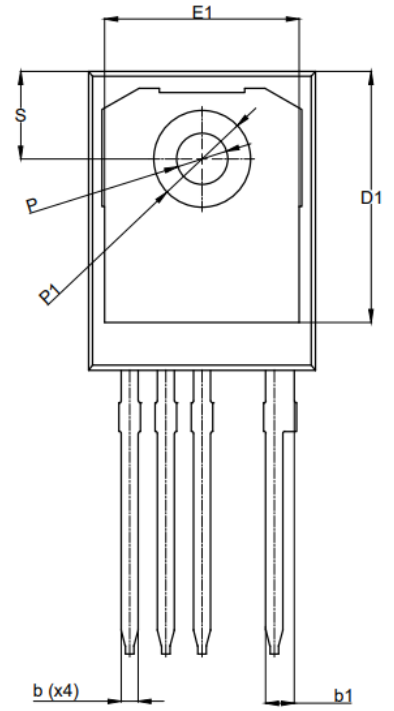
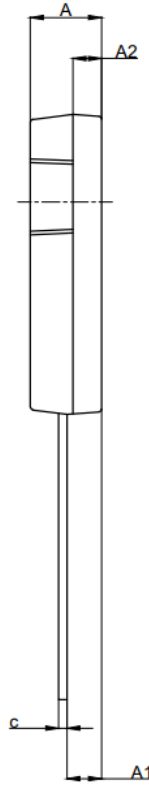
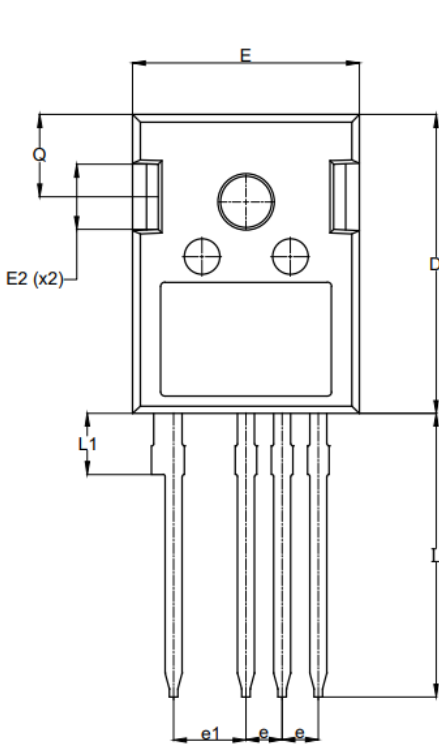


Figure 22. Peak Diode Recovery dv/dt Test Circuit and Waveforms



Package Outlines

TO-247-4L



SYMBOL	Common		
	DIMENSIONS MILLIMETER		
	MIN.	NOM.	MAX.
A	4.80	5.00	5.20
A1	2.29	2.42	2.54
A2	1.90	2.00	2.10
b	1.10	1.20	1.30
b1	1.86	2.01	2.15
c	0.50	0.60	0.70
D	20.90	21.00	21.10
D1	17.43	17.63	17.83
E	15.75	15.94	16.13
E1	13.46	13.66	13.86
E2	4.32	4.58	4.83
e	2.54 BSC.		
e1	5.08 BSC.		
L	19.80	19.95	20.10
L1	-	-	4.30
P	3.56	3.61	3.66
P1	6.75	6.80	6.85
Q	5.38	5.79	6.20
S	6.15 BSC.		

* Dimensions in millimeters

**Package Marking and Ordering Information**

Part Number	Top Marking	Package	Packing Method	Quantity
BCZ120N16M1	BCZ120N16M1	TO-247-4L	Tube	30 units

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